



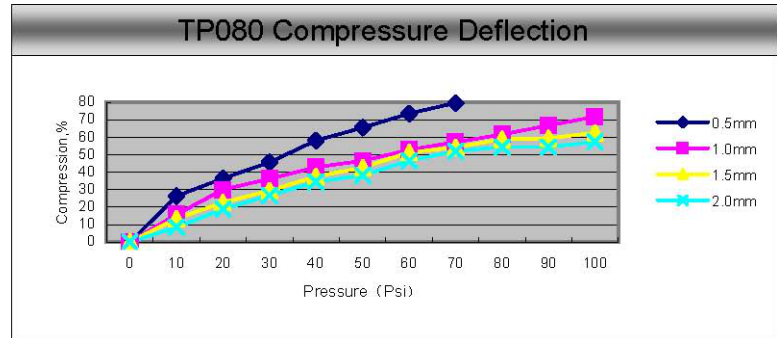
TP080 Series Thermally Conductive Gap Filler Thermal Interface Materials

Features:

- 0.8W/m.k thermal conductivity
- High conformability and cost effective
- Naturally tacky
- Electrically insulating

Applications:

- Between electronic components such as Semiconductor, IC, CPU.MOS and heatsink.
- Led Lighting, Solar Panel, Telecom device, wireless Hub, Battery, power supply etc
- Cooling Module, Memory modules



Typical Properties of TP080

Properties	Units	TP080	Test Method
Construction & Composition	----	Silicone & Ceramic filled	----
Color	----	Gray	Visual
Thickness Range	mm	0.5~12.0	----
Hardness	Shore C	18	ASTM D2240
Density	g/cc	2.0	ASTM D792
Tensile Strength	KN/m	1.3	ASTM D412
Elongation	%	1.35	ASTM D412
Continuous Use Temp	°C	-40 to 150	EN344
Breakdown Voltage	Kv/mm	≥4.0	ASTM D149
Volume Impedance	ohm-cm	1.7×10^{16}	ASTM D257
Dielectric Constant	1MHz	4.51	ASTM D150
Weight Damnify	----	≤1 %	@150°C 240H
Flame Rating	----	V0	UL 94
Thermal Conductivity	W/m.k	0.8	ASTM D5470
UL, RoHS, REACH	----	Compliance	----

Sheet sizes:

Standard sheet size:200x400mm, 330x330mm; Custom Die-cut parts available; Available with or without PSA

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